



# FGA90N30

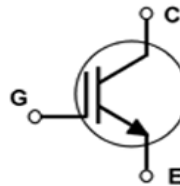
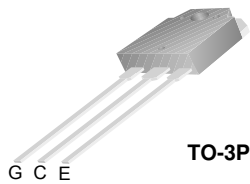
## 300V PDP IGBT

### Features

- High Current Capability
- Low saturation voltage:  $V_{CE(sat)}$ , Typ = 1.1V@  $I_C = 20A$
- High Input Impedance

### Description

Employing Unified IGBT Technology, FGA90N30 provides low conduction and switching loss. FGA90N30 offers the optimum solution for PDP applications where low conduction loss is essential.



### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Description	FGA90N30	Units	
$V_{CES}$	Collector-Emitter Voltage	300	V	
$V_{GES}$	Gate-Emitter Voltage	$\pm 30$	V	
$I_C$	Collector Current	@ $T_C = 25^\circ\text{C}$	90	A
$I_{CM}$	Pulsed Collector Current (Note 1)	@ $T_C = 25^\circ\text{C}$	220	A
$P_D$	Maximum Power Dissipation	@ $T_C = 25^\circ\text{C}$	219	W
	Maximum Power Dissipation	@ $T_C = 100^\circ\text{C}$	87	W
$T_J$	Operating Junction Temperature	-55 to +150	$^\circ\text{C}$	
$T_{stg}$	Storage Temperature Range	-55 to +150	$^\circ\text{C}$	
$T_L$	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$	

**Notes:**

(1) Repetitive test , pulse width = 100usec , Duty = 0.2

\*  $I_{c\_pulse}$  limited by max  $T_J$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case for IGBT	--	0.57	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	--	40	$^\circ\text{C/W}$

## Package Marking and Ordering Information

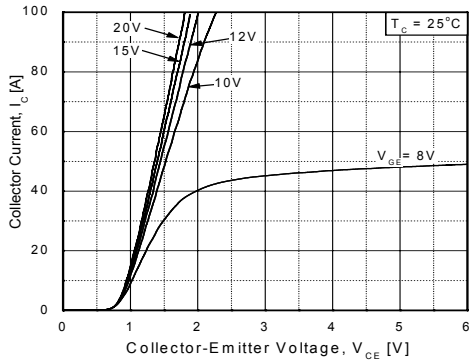
Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FGA90N30	FGA90N30	TO-3P	--	--	30

## Electrical Characteristics of the IGBT T<sub>C</sub> = 25°C unless otherwise noted

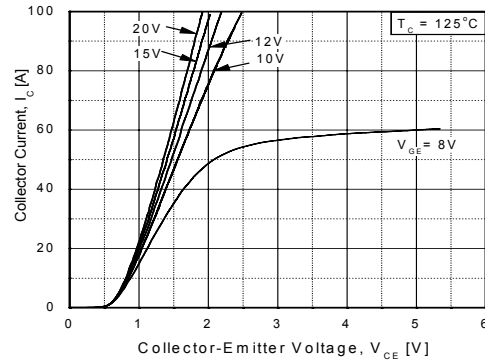
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_C = 250\mu A$	300	--	--	V
$\frac{\Delta BV_{CES}}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V, I_C = 250\mu A$	--	0.6	--	V/°C
$I_{CES}$	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	--	--	100	$\mu A$
$I_{GES}$	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	--	--	$\pm 250$	nA
<b>On Characteristics</b>						
$V_{GE(th)}$	G-E Threshold Voltage	$I_C = 250\mu A, V_{CE} = V_{GE}$	2.5	4.0	5.0	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C = 20A, V_{GE} = 15V$	--	1.1	1.4	V
		$I_C = 90A, V_{GE} = 15V$	--	1.9	--	V
		$I_C = 90A, V_{GE} = 15V, T_C = 125^\circ C$	--	2.0	--	V
<b>Dynamic Characteristics</b>						
$C_{ies}$	Input Capacitance	$V_{CE} = 30V, V_{GE} = 0V, f = 1MHz$	--	1700	-	pF
$C_{oes}$	Output Capacitance		--	290	-	pF
$C_{res}$	Reverse Transfer Capacitance		--	80	-	pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 200V, I_C = 20A, R_G = 10\Omega, V_{GE} = 15V, \text{Resistive Load}, T_C = 25^\circ C$	--	30	--	ns
$t_r$	Rise Time		--	200	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	110	--	ns
$t_f$	Fall Time		--	140	300	ns
$E_{on}$	Turn-On Switching Loss		--	0.15	--	mJ
$E_{off}$	Turn-Off Switching Loss		--	0.45	--	mJ
$E_{ts}$	Total Switching Loss		--	0.6	--	mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC} = 200V, I_C = 20A, R_G = 10\Omega, V_{GE} = 15V, \text{Resistive Load}, T_C = 125^\circ C$	--	30	--	ns
$t_r$	Rise Time		--	210	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	110	--	ns
$t_f$	Fall Time		--	200	--	ns
$E_{on}$	Turn-On Switching Loss		--	0.16	--	mJ
$E_{off}$	Turn-Off Switching Loss		--	0.72	--	mJ
$E_{ts}$	Total Switching Loss		--	0.88	--	mJ
$Q_g$	Total Gate Charge	$V_{CE} = 200V, I_C = 20A, V_{GE} = 15V$	--	87	130	nC
$Q_{ge}$	Gate-Emitter Charge		--	12	18	nC
$Q_{gc}$	Gate-Collector Charge		--	38	57	nC

## Typical Performance Characteristics

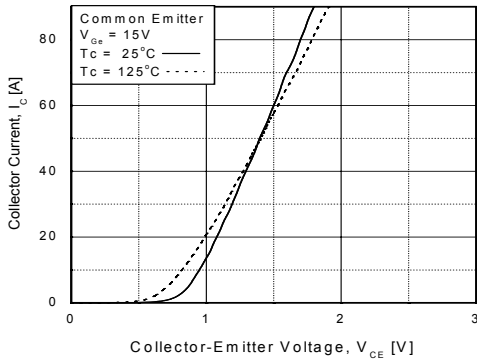
**Figure 1. Typical Output Characteristics**



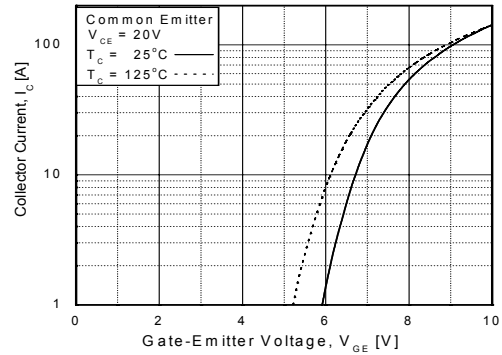
**Figure 2. Typical Output Characteristics**



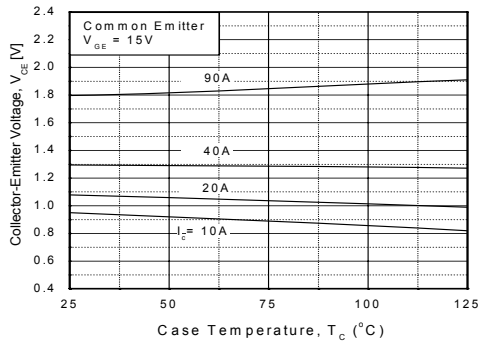
**Figure 3. Typical Saturation Voltage Characteristics**



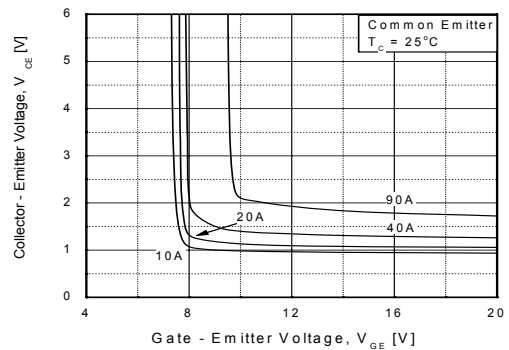
**Figure 4. Transfer characteristics**



**Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level**

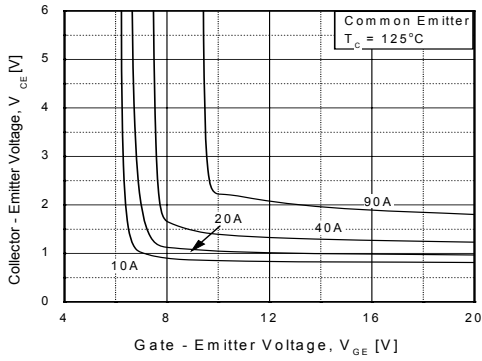


**Figure 6. Saturation Voltage vs. Vge**

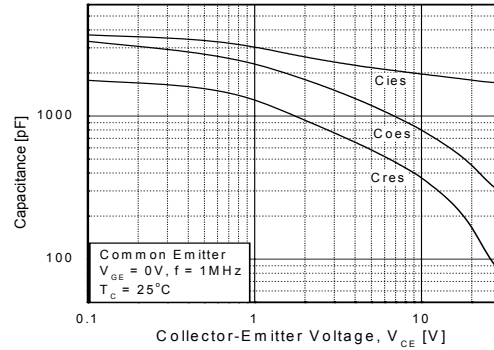


**Typical Performance Characteristics** (Continued)

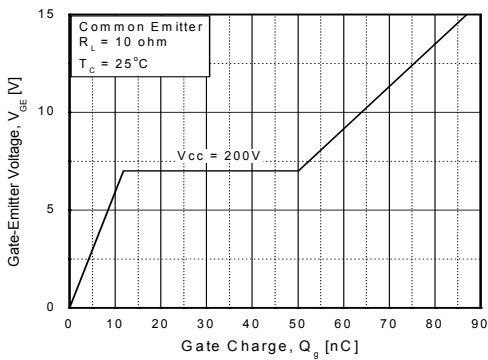
**Figure 7. Saturation Voltage vs.  $V_{GE}$**



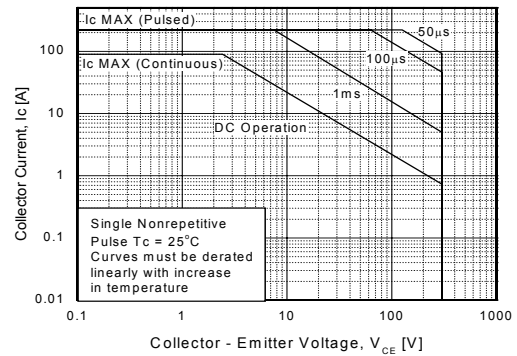
**Figure 8. Capacitance Characteristics**



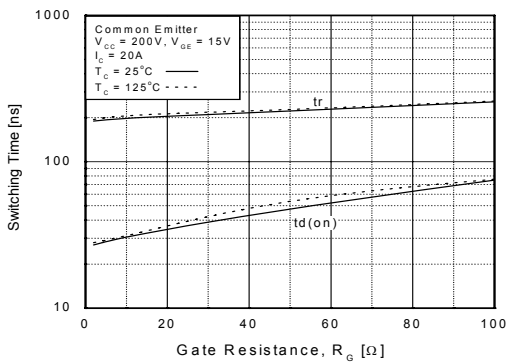
**Figure 9. Gate Charge Characteristics**



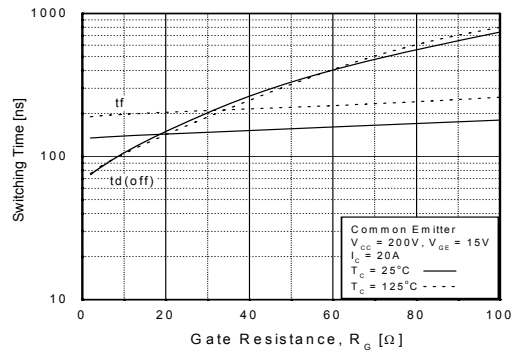
**Figure 10. SOA Characteristics**



**Figure 11. Turn-On Characteristics vs. Gate Resistance**

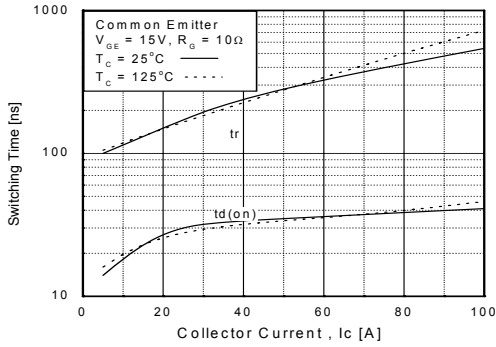


**Figure 12. Turn-Off Characteristics vs. Gate Resistance**

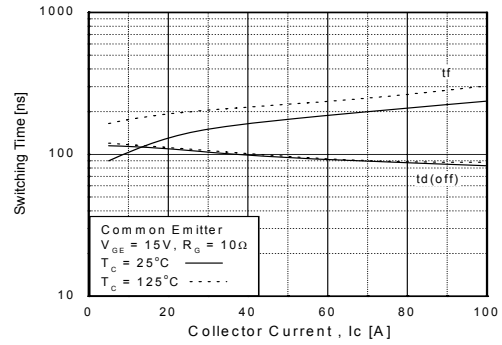


**Typical Performance Characteristics** (Continued)

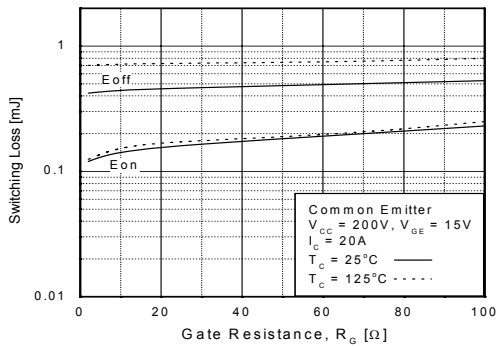
**Figure 13. Turn-On Characteristics vs. Collector Current**



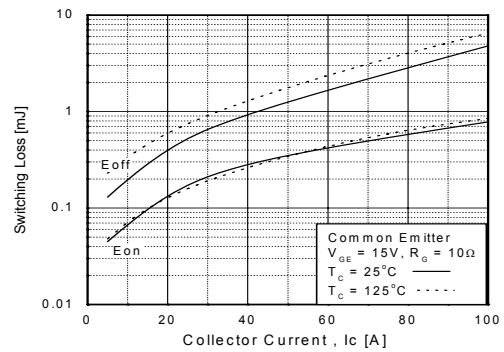
**Figure 14. Turn-Off Characteristics vs. Collector Current**



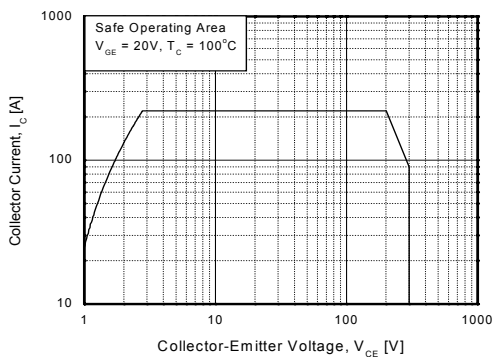
**Figure 15. Switching Loss vs. Gate Resistance**



**Figure 16. Switching Loss vs. Collector Current**

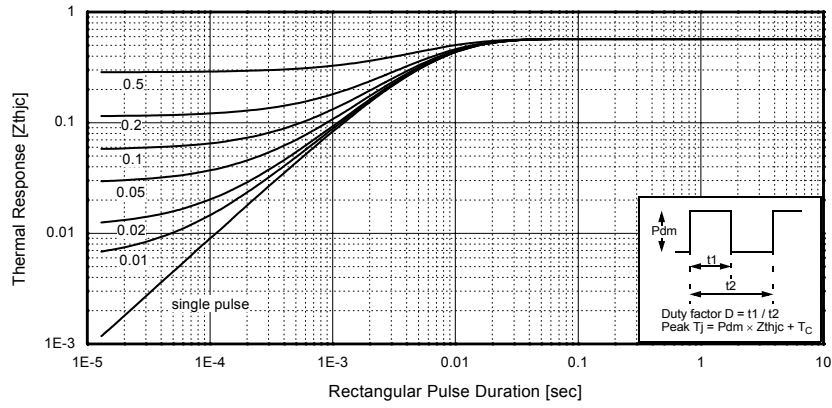


**Figure 17. Turn-Off SOA Figure**



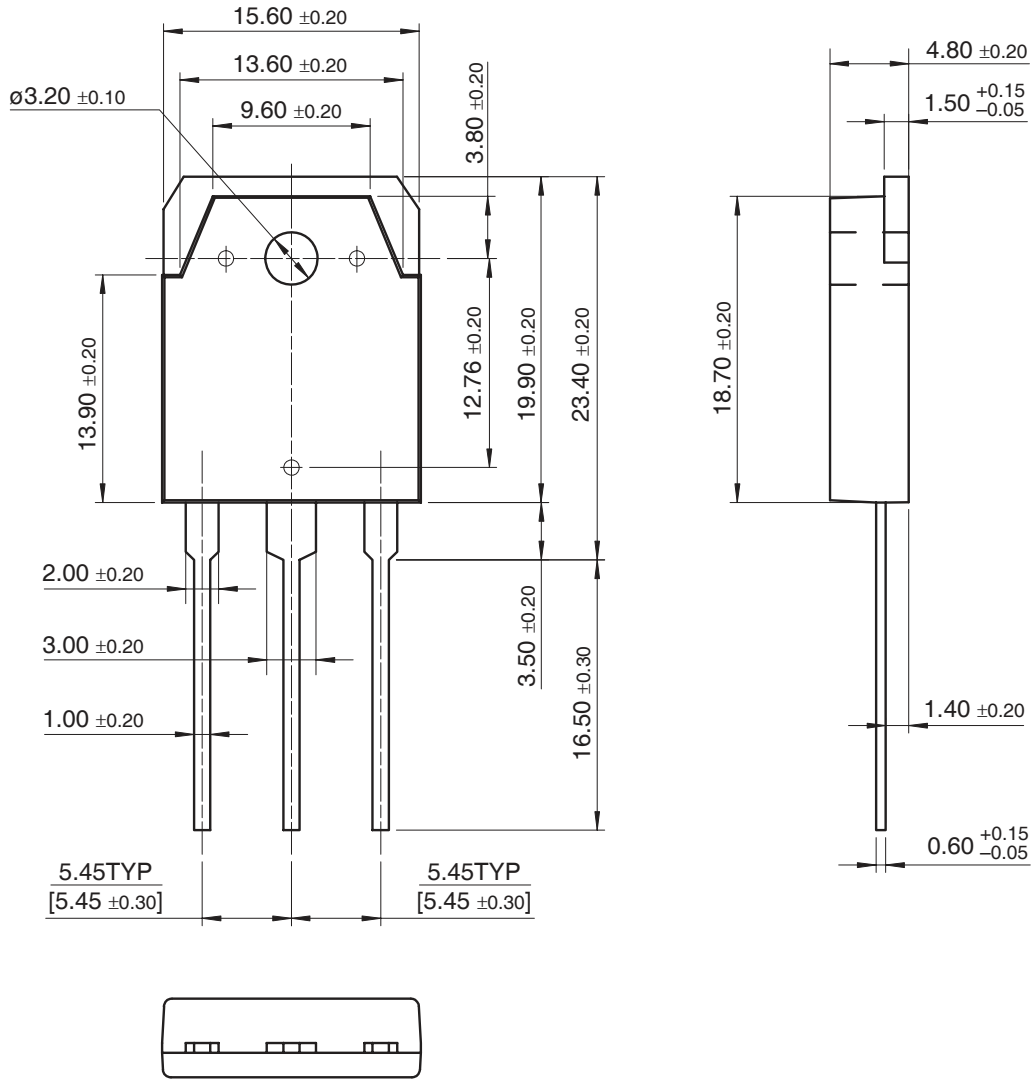
Typical Performance Characteristics (Continued)

Figure 18. Transient Thermal Impedance of IGBT



Mechanical Dimensions

TO-3P



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## FGA90N30

300V PDP IGBT

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### General description

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### Features

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- Low saturation voltage:  $V_{CE(sat)}$ , Typ = 1.1V@  $I_C = 20A$
- High Input Impedance

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### Product status/pricing/packageing

**BUY**

Product	Product status	Pb-free Status	Pricing*	Package type	Leads	Packing method	Package Marking Convention**
FGA90N30TU	Full Production	 Full Production	\$3.42	<a href="#">TO-3P</a>	3	RAIL	Line 1: \$Y (Fairchild logo) Line 2: FGA90N30 Line 3: &3

\* Fairchild 1,000 piece Budgetary Pricing

\*\* A sample button will appear if the part is available through Fairchild's on-line samples program. If there is no sample button, please contact a [Fairchild distributor](#) to obtain samples

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Package marking information for product FGA90N30 is available. [Click here for more information](#).

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Product
<a href="#">FGA90N30TU</a>

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